Docket No.: 6/352-04/

DECLARATION AND POWER OF ATTORNEY FOR APPLICATION UNDER 35 USC 111(a)

As a below named inventor, I hereby declare that:

My residence, post office and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter claimed and for which a patent is sought on the invention entitled METHOD OF FABRICATING NITRIDE BASED SEMICONDUCTOR SUBSTRATE AND METHOD OF FABRICATING NITRIDE BASED SEMICONDUCTOR DEVICE, the specification of which

_		
is attached hereto		
was filed on	as Application Serial No.	and was amended or
(if applicable)	• •	

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is known to me to be material to patentability in accordance with Title 37, Code of Federal Regulations, Section 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, Section 119 or Section 365 of any foreign and/or International (PCT) application(s) for patent or inventor's certificate listed below, and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Applications(s):

Number	Country	Day/Month/Year filed	Priority Claimed
PCT/JP02/13350	PCT	December 20, 2002	
2001-387033	Japan	December 20, 2001	\bowtie

I hereby claim the benefit under 35 USC §119(e) of any United States provisional application(s) listed below.

Prior Provisional Application(s):

Application Number Filing Date

I hereby claim the benefit under Title 35, United States Code, Section 120 or 365 of any United States and/or International (PCT) application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Section 1.56 which occurred between the filing date of the prior application and the national or International (PCT) filing date of this application:

Prior U.S. Application(s):

Serial No. Filing Date Status: Patented, Pending, Abandoned

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge

that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint the following attorney(s) and/or agent(s): Steven W. Allis, Reg. No. 50,532; Stephen A. Becker, Reg. No. 26,527; John G. Bisbikis, Reg. No. 37,095; Daniel Bucca, Reg. No. 42,368; Kenneth L. Cage, Reg. No. 26,151; Jennifer Chen, Reg. No. 42,404; Bernard P. Codd, Reg. No. 46,429; Lawrence T. Cullen, Reg. No. 44,489; Paul Devinsky, Reg. No. 28,553; Margaret M. Duncan, Reg. No. 30,879; Shamita De. Etienne-Cummings, Reg. No. 46,072; Ramyar M. Farid, Reg. No. 46,692; Brian E. Ferguson, Reg. No. 36,801; Michael E. Fogarty, Reg. No. 36,139; John R. Fuisz, Reg. No. 37,327; Willem F. Gadiano, Reg. No. 37,136; Keith E. George, Reg. No. 34,111; John A. Hankins, Reg. No. 32,029; Eric J. Kraus, Reg. No. 36,190; Catherine Krupka, Reg. No. 46,227; Jack Q. Lever, Reg. No. 28,149; Raphael V. Lupo, Reg. No. 28,363; Burman Y. Mathis III, Reg. No. 44,907; Michael A. Messina, Reg. No. 33,424; Dawn L. Palmer, Reg. No. 41,238; Joseph H. Paquin, Jr., Reg. No. 31,647; Scott D. Paul, Reg. No. 42,984; William D. Pegg, Reg. No. 42,988; Robert L. Price, Reg. No. 22,685; Gene Z. Rubinson, Reg. No. 33,351; Brian K. Seidleck, Reg. No. 51,321; Joy Ann G. Serauskas, Reg. No. 27,952; Jiri F. Smetana, Reg. No. 52,456; David A. Spenard, Reg. No. 37,449; Arthur J. Steiner, Reg. No. 26,106; Wesley Strickland, Reg. No. 44,363; Michael D. Switzer, Reg. No. 39,552; David M. Tennant, Reg. No. 48,362; Judith L. Toffenetti, Reg. No. 39,048; Daniel S. Trainor, Reg. No. 43,959; Shival P. Virmani, Reg. No. 45,032; Kelli N. Watson, Reg. No. 47,170; Cameron K. Weiffenbach, Reg. No. 44,488; Aaron Weisstuch, Reg. No. 41,557; Edward J. Wise, Reg. No. 34,523; Jeffrey A. Woller, Reg. No. 48,041; Alexander V. Yampolsky, Reg. No. 36,324; Robert W. Zelnick, Reg. No. 36,976; and Wei-Chen Chen, admitted under 37 CFR 10.9(b) all of

MCDERMOTT, WILL & EMERY 600 13th Street, NW Washington, DC 20005-3096

with full power of substitution and revocation, to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith, and all future correspondence should be addressed to them.

Full name of sole or first inventor: Hiroyuki FURUYA		
Inventor's signature: Hirographi Juruya	Date:	July , 8, 2003
Residence: Nara-shi, Nara, JAPAN		7
Citizenship: Japanese		
Post Office Address: 1-6-24-403, Jingu, Nara-shi, Nara 631-0804 JAPAN		
Full name of second inventor: Toshiya YOKOGAWA		
Inventor's signature: Joshiya Yohogawa Regidence: New ski New 14 BAN	Date:	July , 8 . 2003
Residence: Nara-shi, Nara, JAPAN		9 9
Citizenship: Japanese		
Post Office Address: 5-2-24, Aoyama, Nara-shi, Nara 630-8101 JAPAN		

Full name of third inventor: Akihiko ISHIBASHI	
Inventor's signature: akihiko Shibash	Date: July 8, 2000
Residence: Mishima-gun, Osaka, JAPAN	
Citizenship: Japanese	
Post Office Address: 2-2220-301, Todaiji, Shimamoto-cho, Mishima-gun, Osaka 618-0002 JAPAN	
Full name of fourth inventor: Yoshiaki HASEGAWA	
Inventor's signature: Yoshiaki Zasegawa	Date: July 8, 2003
Residence: Katano-shi, Osaka, JAPAN	
Citizenship: Japanese	*
Post Office Address: 4-9-401, Ikuno, Katano-shi, Osaka 576-0054 JAPAN	